



Material Content Data Sheet



Sales Product Name		BFR 93AW H6327		Issued		24. January 2018		
MA#		MA001190804						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.01		90	
	noble metal	gold	7440-57-5	0.002	0.03		348	
	inorganic material	silicon	7440-21-3	0.018	0.30	0.34	3002	3440
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1324	
	non noble metal	copper	7440-50-8	2.617	43.94	44.12	439389	441242
wire	noble metal	gold	7440-57-5	0.008	0.13	0.13	1318	1318
	encapsulation	organic material	carbon black	0.032	0.53		5300	
	plastics	epoxy resin	-	0.679	11.40		113958	
	inorganic material	silicondioxide	60676-86-0	2.447	41.08	53.01	410780	530038
leadfinish	non noble metal	tin	7440-31-5	0.133	2.23	2.23	22281	22281
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1681	1681
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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